# HSMS-8101, 8202, 8207, 8209

# Surface Mount Microwave Schottky Mixer Diodes



# **Data Sheet**

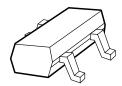


#### **Description/Applications**

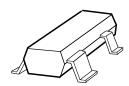
These low cost microwave Schottky diodes are specifically designed for use at X/Ku-bands and are ideal for DBS and VSAT downconverter applications. They are available in SOT-23 and SOT-143 standard package configurations.

Note that Avago's manufacturing techniques assure that dice found in pairs and quads are taken from adjacent sites on the wafer, assuring the highest degree of match.

#### Plastic SOT-23 Package



#### Plastic SOT-143 Package



## Absolute Maximum Ratings<sup>[1]</sup>, $T_A = +25^{\circ}C$

Symbol	Parameter	Unit	Min.	Max.
P <sub>T</sub>	Total Device Dissipation <sup>[2]</sup>	mW	_	75
P <sub>IV</sub>	Peak Inverse Voltage	V	_	4
T <sub>J</sub>	Junction Temperature	°C	_	+150
T <sub>STG</sub> , T <sub>op</sub>	Storage and Operating Temperature	°C	-65	+150

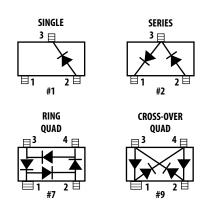
#### Notes:

- Operation in excess of any one of these conditions may result in permanent damage to the device.
- Measured in an infinite heat sink at T<sub>CASE</sub> = 25°C. Derate linearly to zero at 150°C per diode.

#### **Features**

- Optimized for use at 10-14 GHz
- Low Capacitance
- Low Conversion Loss
- Low RD
- Low Cost Surface Mount Plastic Package
- Lead-free

# Package Lead Code Identification (Top View)





Attention: Observe precautions for handling electrostatic sensitive devices. ESD Machine Model (Class A) ESD Human Body Model (Class 0) Refer to Avago Application Note A004R: Electrostatic Discharge Damage and Control.

# DC Electrical Specifications, $T_A = 25^{\circ}C$

			HSMS	5-8101	HSMS	5-8202	HSMS	-8207	HSMS	-8209
Symbol	Parameters and Test Conditions	Units	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
$V_{BR}$	Breakdown Voltage I <sub>R</sub> = 10 μA	V	4		4		4		4	
C <sub>T</sub>	Total Capacitance V <sub>R</sub> = 0 V, f = 1 MHz	pF		0.26		0.26		0.26		0.26
DC <sub>T</sub>	Capacitance Difference $V_R = 0 V, f = 1 MHz$	pF		_		0.04		0.04		0.04
R <sub>D</sub>	Dynamic Resistance I <sub>F</sub> = 5 mA	Ω		14		14		14		14
DR <sub>D</sub>	Dynamic Resistance Difference I <sub>F</sub> = 5 mA	Ω		_		2		2		2
V <sub>F</sub>	Forward Voltage I <sub>F</sub> = 1 mA	mV	250	350	250	350	250	350	250	350
DV <sub>F</sub>	Forward Voltage Difference I <sub>F</sub> = 1 mA	mV		_		20		20		20
	Lead Code			1		2		7	9	9
	Package Marking Code where x is date code		R	1x	2	Rx	R	7x	R	9x

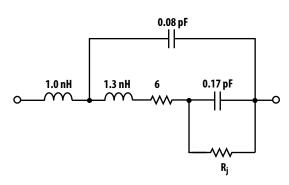
# RF Electrical Parameters, $T_A = 25$ °C

Symbol	Parameter	Units	Typical
L <sub>c</sub>	Conversion Loss at 12 GHz	dB	6.3
Z <sub>IF</sub>	IF Impedance	Ω	150
SWR	SWR at 12 GHz		1.2

#### Note:

DC Load Resistance =  $0 \Omega$ ; LO Power = 1 mW.

# **Linear Equivalent Circuit**



## **SPICE Parameters**

I <sub>s</sub> = 4.6 E-8	$E_{G} = 0.69$	TT = 0
$R_s = 6$	$C_{JO} = 0.18 E-12$	
N = 1.09	$P_{B}(V_{J}) = 0.5$	
B <sub>v</sub> = 7.3	M = 0.5	
I <sub>BV</sub> = 10E-5	FC = 0.5	

# **Self Bias**

	1 mA	2.5 mA
R <sub>i</sub>	256	142

## Typical Performance, $T_c = 25^{\circ}C$

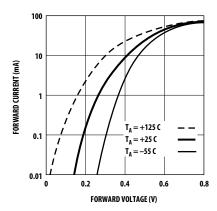


Figure 1. Typical Forward Current vs. Forward Voltage at Three Temperatures.

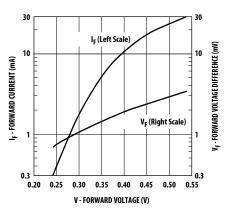


Figure 2. Typical VF Match, HSMS-820X Pairs and Quads.

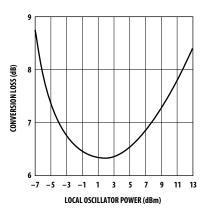
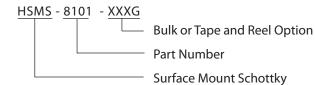


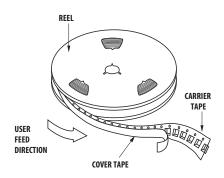
Figure 3. Typical Conversion Loss vs. Local Oscillator Power.

#### **Ordering Information**

Specify part number followed by option. For example:



### **Device Orientation**



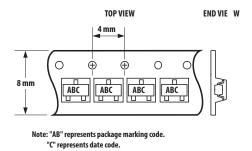


Figure 4. Option -TR1G/-TR2G for SOT-23 Packages.

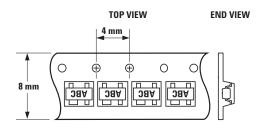
#### **Profile Option Descriptions**

-BLKG = Bulk

-TR1G = 3K pc. Tape and Reel, Device Orientation Figures 4, 5

-TR2G = 10K pc. Tape and Reel, Device Orientation Figures 4, 5

Tape and Reeling conforms to Electronic Industries RS-481, "Taping of Surface Mounted Components for Automated Placement."



Note: "AB" represents package marking code.
"C" represents date code.

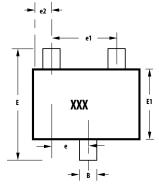
Figure 5. Option -TR1G/-TR2G for SOT-143 Packages.

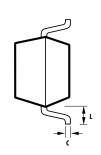
# **Package Characteristics**

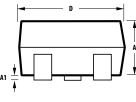
Lead Material	Alloy 42
Lead Finish	Tin 100% (Lead-free option)
Maximum Soldering Temperature	260°C for 5 seconds
Minimum Lead Strength	2 pounds pull
Typical Package Inductance	2 nH
Typical Package Capacitance	0.08 pF (opposite leads)

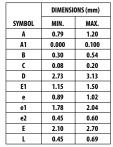
## **Package Dimensions**

# Outline 23 (SOT-23)

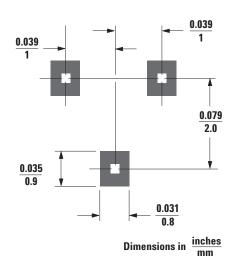






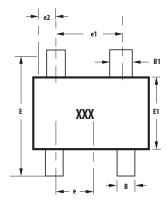


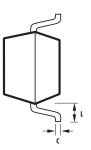
# Recommended PCB Pad Layout for Avago's SOT-23 **Products**



### Outline 143 (SOT-143)

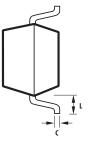
XXX-package marking Drawings are not to scale





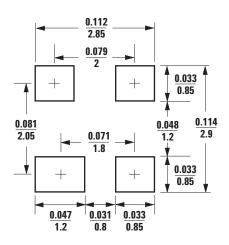
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XXX-package marking Drawings are not to scale

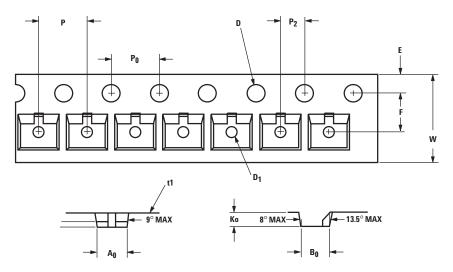


	DIMENSIONS (mm)		
SYMBOL	MIN.	MAX.	
Α	0.79	1.097	
A1	0.013	0.10	
В	0.36	0.54	
B1	0.76	0.92	
C	0.086	0.152	
D	2.80	3.06	
E1	1.20	1.40	
e	0.89	1.02	
e1	1.78	2.04	
e2	0.45	0.60	
E	2.10	2.65	
L	0.45	0.69	

# **Recommended PCB Pad Layout for Avago's SOT-143 Products**

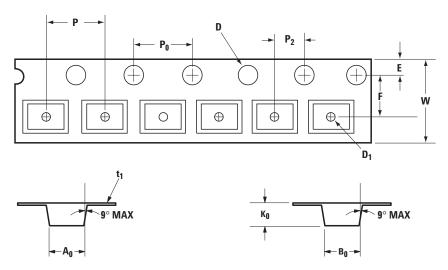


# Tape Dimensions and Product Orientation For Outline SOT-23



	DESCRIPTION	SYMBOL	SIZE (mm)	SIZE (INCHES)
CAVITY	LENGTH	A <sub>0</sub>	$3.15 \pm 0.10$	$0.124 \pm 0.004$
	WIDTH	B <sub>0</sub>	$2.77 \pm 0.10$	$0.109 \pm 0.004$
	DEPTH	K <sub>0</sub>	$1.22 \pm 0.10$	$\textbf{0.048} \pm \textbf{0.004}$
	PITCH	P	$4.00 \pm 0.10$	$0.157 \pm 0.004$
	BOTTOM HOLE DIAMETER	D <sub>1</sub>	1.00 + 0.05	$\textbf{0.039} \pm \textbf{0.002}$
PERFORATION	DIAMETER	D	1.50 + 0.10	0.059 + 0.004
	PITCH	Po	$4.00 \pm 0.10$	$0.157 \pm 0.004$
	POSITION	E	1.75 $\pm$ 0.10	$\textbf{0.069} \pm \textbf{0.004}$
CARRIER TAPE	WIDTH	w	8.00 + 0.30 - 0.10	0.315 + 0.012 - 0.004
	THICKNESS	t1	$0.229 \pm 0.013$	0.009 0.0005
DISTANCE BETWEEN	CAVITY TO PERFORATION (WIDTH DIRECTION)	F	$3.50\pm0.05$	0.138 ± 0.002
CENTERLINE	CAVITY TO PERFORATION (LENGTH DIRECTION)	P <sub>2</sub>	$\textbf{2.00} \pm \textbf{0.05}$	$0.079 \pm 0.002$

# Tape Dimensions and Product Orientation For Outline SOT-143



	DESCRIPTION	SYMB0L	SIZE (mm)	SIZE (INCHES)
CAVITY	LENGTH	A <sub>0</sub>	$\textbf{3.19} \pm \textbf{0.10}$	$0.126 \pm 0.004$
	WIDTH	B <sub>0</sub>	$\textbf{2.80} \pm \textbf{0.10}$	$0.110 \pm 0.004$
	DEPTH	K <sub>0</sub>	1.31 $\pm$ 0.10	$\textbf{0.052} \pm \textbf{0.004}$
	PITCH	P	$\textbf{4.00} \pm \textbf{0.10}$	$0.157 \pm 0.004$
	BOTTOM HOLE DIAMETER	D <sub>1</sub>	1.00 + 0.25	0.039 + 0.010
PERFORATION	DIAMETER	D	1.50 + 0.10	0.059 + 0.004
	PITCH	P <sub>0</sub>	$\textbf{4.00} \pm \textbf{0.10}$	$0.157 \pm 0.004$
	POSITION	E	$1.75 \pm 0.10$	$0.069 \pm 0.004$
CARRIER TAPE	WIDTH	W	8.00 + 0.30 - 0.10	0.315+0.012 - 0.004
	THICKNESS	t1	$\textbf{0.254} \pm \textbf{0.013}$	$0.0100\pm0.0005$
DISTANCE	CAVITY TO PERFORATION (WIDTH DIRECTION)	F	$\textbf{3.50} \pm \textbf{0.05}$	$0.138 \pm 0.002$
	CAVITY TO PERFORATION (LENGTH DIRECTION)	P <sub>2</sub>	$\textbf{2.00} \pm \textbf{0.05}$	$0.079 \pm 0.002$

For product information and a complete list of distributors, please go to our web site: **www.avagotech.com** 

